

# Dual N-Channel 60 V (D-S) 175 °C MOSFET

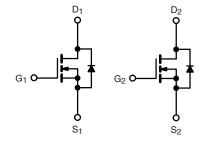
PRODUCT SUMMARY				
V <sub>DS</sub> (V)	60			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.028			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 \text{ V}$	0.030			
I <sub>D</sub> (A) per leg	7			
Configuration	Dual			

# SO-8 Dual $\begin{array}{c} D_2 \\ D_2 \\ D_1 \\ 7 \\ 8 \\ \end{array}$ $\begin{array}{c} D_2 \\ 5 \\ \end{array}$ $\begin{array}{c} D_3 \\ G_2 \\ \end{array}$ $\begin{array}{c} 3 \\ G_2 \\ \end{array}$ $\begin{array}{c} G_2 \\ \end{array}$ $\begin{array}{c} Top \ View \\ \end{array}$

#### **FEATURES**

- TrenchFET® power MOSFET
- 100 % R<sub>q</sub> and UIS tested





N-Channel MOSFET N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	<b>S</b> (T <sub>C</sub> = 25 °C, unles	s otherwise noted	i)		
PARAMETER	SYMBOL	LIMIT	UNIT		
Drain-Source Voltage		V <sub>DS</sub>	60	.,,	
Gate-Source Voltage		$V_{GS}$	± 20	V	
Continuous Drain Current	T <sub>C</sub> = 25 °C	1	7		
Continuous Drain Current	T <sub>C</sub> = 125 °C	- I <sub>D</sub>	4		
Continuous Source Current (Diode Conduction) <sup>a</sup>		I <sub>S</sub>	3.6	Α	
Pulsed Drain Current <sup>b</sup>		I <sub>DM</sub>	28		
Single Pulse Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	18		
Single Pulse Avalanche Energy	L = 0.1 IIII	E <sub>AS</sub>	16.2	mJ	
Maximum Power Dissipation <sup>b</sup>	T <sub>C</sub> = 25 °C	D	4	W	
	T <sub>C</sub> = 125 °C	$P_{D}$	1.3	VV	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C	

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	LIMIT	UNIT		
Junction-to-Ambient	PCB Mount <sup>c</sup>	$R_{thJA}$	110	°C/W		
Junction-to-Foot (Drain)		$R_{thJF}$	34	C/VV		

#### Notes

- a. Package limited.
- b. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- c. When mounted on 1" square PCB (FR4 material).



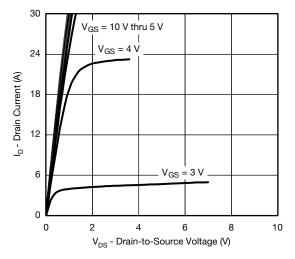
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		60	-	-	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	$V_{DS} = V_{GS}, I_D = 250 \mu A$		2.0	2.5	V
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 60 V	-	-	1	μА
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{GS} = 0 V$	$V_{DS} = 60 \text{ V}, T_{J} = 125 ^{\circ}\text{C}$	-	-	50	
		$V_{GS} = 0 V$	V <sub>DS</sub> = 60 V, T <sub>J</sub> = 175 °C		-	150	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>GS</sub> = 10 V	$V_{DS} \ge 5 V$	20	-	-	Α
		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 4.5 A-		0.028	-	Ω
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 4.5 A, T <sub>J</sub> = 125 °C	-	0.066	-	
Brain Godree on Glate Hosiotanoe	1 (DS(on)	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 4.5 A, T <sub>J</sub> = 175 °C	-	0.081	-	
		$V_{GS} = 4.5 \text{ V}$	I <sub>D</sub> = 4 A-		0.030	-	
Forward Transconductance f	9fs	$V_{DS} = 15 \text{ V}, I_D = 4.5 \text{ A}$			15	-	S
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			-	600	750	
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 V$	V <sub>DS</sub> = 25 V, f = 1 MHz	-	110	140	pF
Reverse Transfer Capacitance	C <sub>rss</sub>	]		-	50	62	
Total Gate Charge <sup>c</sup>	Qg			-	11.7	18	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	$V_{DS} = 30 \text{ V}, I_{D} = 5.3 \text{ A}$	-	1.8	2.7	nC
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>	1		-	2.8	4.2	
Gate Resistance	$R_g$	f = 1 MHz		1.3	-	6	Ω
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>				7	11	
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 30 \text{ V}, \text{ R}_L = 6.8 \ \Omega$ $I_D \cong 4.4 \text{ A}, \text{ V}_{GEN} = 10 \text{ V}, \text{ R}_g = 1 \ \Omega$		-	3.3	5	ns
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>			-	22.4	33.5	
Fall Time <sup>c</sup>	t <sub>f</sub>			-	2.1	3.2	
Source-Drain Diode Ratings and Chara	acteristics b						
Pulsed Current <sup>a</sup>	I <sub>SM</sub>			-	-	28	Α
Forward Voltage	V <sub>SD</sub>	I <sub>F</sub> = 2 A, V <sub>GS</sub> = 0 V		-	0.75	1.1	V

### Notes

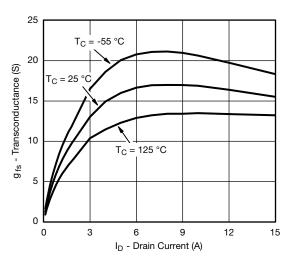
- a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %. b. Guaranteed by design, not subject to production testing. c. Independent of operating temperature.



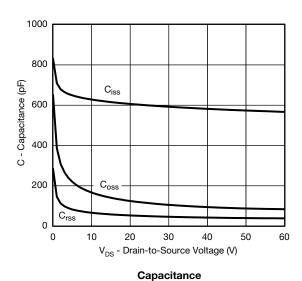
## **TYPICAL CHARACTERISTICS** ( $T_A = 25 \, ^{\circ}\text{C}$ , unless otherwise noted)



#### **Output Characteristics**



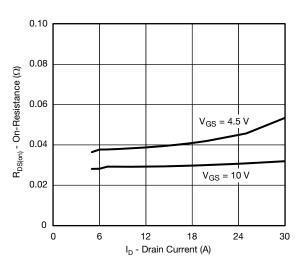
Transconductance



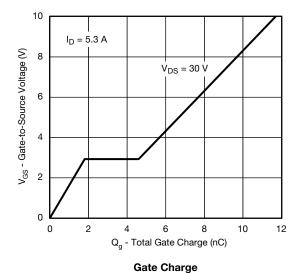
30
24
(2)
18
T<sub>C</sub> = 25 °C
T<sub>C</sub> = 125 °C
T<sub>C</sub> = -55 °C

V<sub>GS</sub> - Gate-to-Source Voltage (V)

**Transfer Characteristics** 



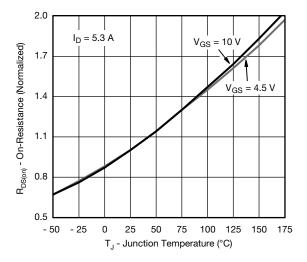
On-Resistance vs. Drain Current



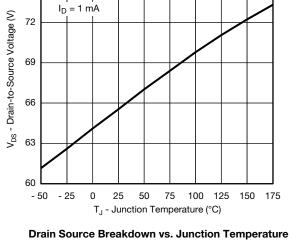
3

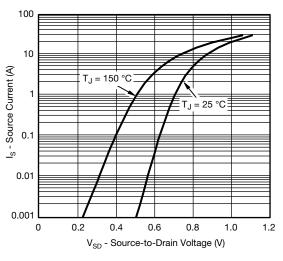


## **TYPICAL CHARACTERISTICS** ( $T_A = 25$ °C, unless otherwise noted)

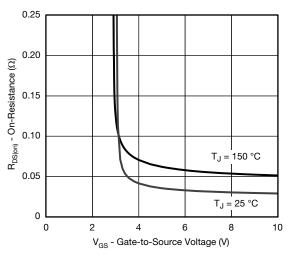


On-Resistance vs. Junction Temperature

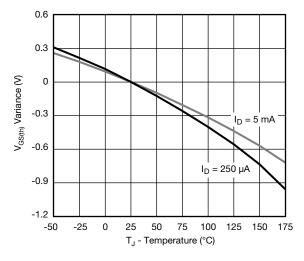




**Source Drain Diode Forward Voltage** 



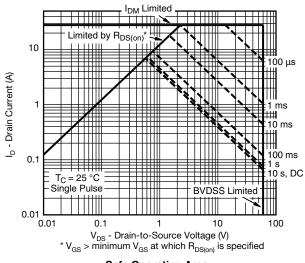
On-Resistance vs. Gate-to-Source Voltage



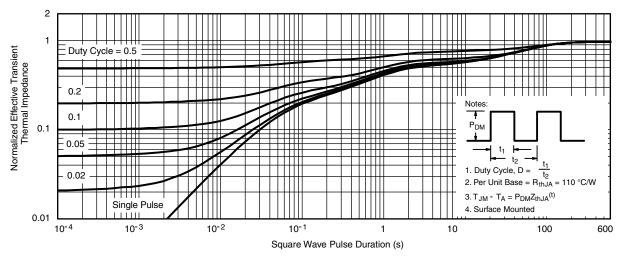
**Threshold Voltage** 



## **THERMAL RATINGS** ( $T_A = 25$ °C, unless otherwise noted)



Safe Operating Area



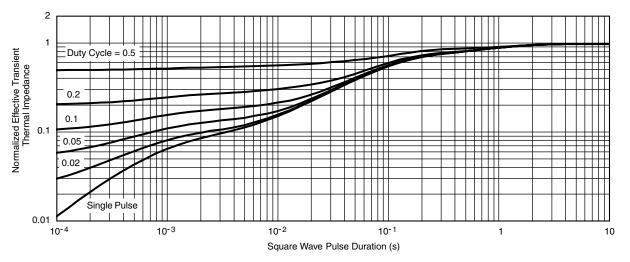
Normalized Thermal Transient Impedance, Junction-to-Ambient

服务热线:400-655-8788

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# **THERMAL RATINGS** ( $T_A = 25~^{\circ}C$ , unless otherwise noted)



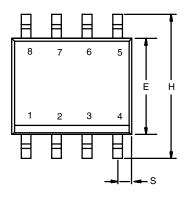
Normalized Thermal Transient Impedance, Junction-to-Foot

服务热线:400-655-8788

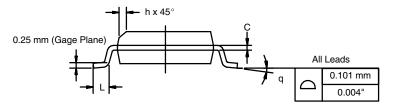
6



SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012





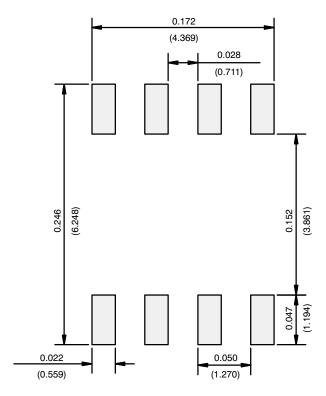


	MILLIM	IETERS	INCHES		
DIM	Min	Max	Min	Max	
Α	1.35	1.75	0.053	0.069	
A <sub>1</sub>	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
Е	3.80	4.00	0.150	0.157	
е	1.27 BSC		0.050 BSC		
Н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	
S	0.44	0.64	0.018	0.026	
ECN: C-0652	27-Rev. I, 11-Sep-0	6			

DWG: 5498



## **RECOMMENDED MINIMUM PADS FOR SO-8**



Recommended Minimum Pads Dimensions in Inches/(mm)



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